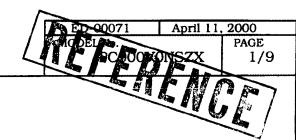
PREPARED BY: DATE:		SPEC. No. ED-00071
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APPROVED BY: DATE:	ELECTRONIC COMPONENTS GROUP SHARP CORPORATION	REPRESENTATIVE DUSIN
K. Kusuda apr 12,2000	SPECIFICATION	OPTO-ELECTRONIC DEVICES DIV
DEVI	CE SPECIFICATION FOR	)
	PHOTOCOUPLER	
MOD	EL No. DCCCOV	
	PC900V	
	(Business dealing name: PC900V0NS2	200
<del></del>		•
1. These specification shorts in	natural materials protected under converight of	Sharn Corneration ("Sharn")
	nclude materials protected under copyright of cause anyone to reproduce them without Shar	
2. When using this product, n	lease observe the absolute maximum ratings a	nd the instructions for use outlined
in these specification sheet	s, as well as the precautions mentioned below.	Sharp assumes no responsibility
	om use of the product which does not comply	
and the instructions includ	led in these specification sheets, and the preca	utions mentioned below.
(Precautions)		
· - ·	esigned for use in the following application area  • Audio visual equipment  • Home appliance	
, , ,	ation equipment (Terminal) • Measuring equi	1 3
	nes · Computers	
If the use of the	product in the above application areas is for eq	
(2) or (3), please	be sure to observe the precautions given in the	se respective paragraphs.
	ures, such as fail-safe design and redundant d	
	of the overall system and equipment, should be his product is used for equipment which dema	
	and precision, such as ;	nds night tenability and
· Transportation	control and safety equipment (aircraft, train,	automobile etc.)
	· Gas leakage sensor breakers · Rescue and	d security equipment
Other safety eq	uipment	
	this product for equipment which require extr	emely high reliability
	tion and precision, such as ; ent · Telecommunication equipment (for trun	k lines)
• Nuclear power	control equipment · Medical equipment	k inics)
_	i consult with a Sharp sales representative if the	here are any questions
	tation of the above three paragraphs.	nere are any questions
3. Please contact and consult v	with a Sharp sales representative for any ques	tions about this product.
	DATE	Apr. 12, 1005
CUSTOMER'S APPROVA	AL PRESENTE	o tor.
	ВУ	Spr. 12, roos 10 for 11. Imenaba
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DATE	Depart	tment General Manager of
		eering Dept.,II Electronic Devices Div.
ВУ		OM Group
		P CORPORATION



### 1. Application

This specification applies to the outline and characteristics of photocoupler Model No. PC900V.

### 2. Outline

Refer to the attached sheet, page 3.

### 3. Ratings and characteristics

Refer to the attached sheet, page 3 to 5.

### 4. Reliability

Refer to the attached sheet, page 8.

### 5. Outgoing inspection

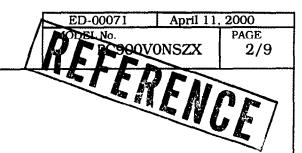
Refer to the attached sheet, page 9.

# 6. Supplement

- 6.1 Isolation voltage shall be measured in the following method.
- (1) Short among pins 1 to 3 on the primary side and among pins 4 to 6 on the secondary side.
- (2) The dielectric withstand tester with zero-cross circuit shall be used.
- (3) The wave form of applied voltage shall be a sine wave. (It is recommended that the isolation voltage be measured in insulation oil.)
- 6.2 The business dealing name used for this product when ordered or delivered shall be PC900V0NSZX.

#### 6.3 Package specifications

Refer to the attached sheets-2-1 to 2-3.



### 6.4 UL: Under preparation

# 6.5 Theory of operation

- (1) When the forward current of above the " $H \rightarrow L$ " threshold input current ( $I_{FHL}$ ) is applied to the input side, the output will go "Low level".
- (2) When the forward current on the input side goes below the " $L \rightarrow H$ " threshold input current ( $I_{FLH}$ ) is applied to the input side, the output will go "High level".
- 6.6 This product is not designed against irradiation.

This product is assembled with electrical input and output.

This product incorporates non-coherent light emitting diode.

#### 6.7 ODS materials

This product shall not contain the following materials.

Also, the following materials shall not be used in the production process for this product.

Materials for ODS: CFC<sub>S</sub>, Halon, Carbon tetrachloride, 1.1.1-Trichloroethane (Methylchloroform)

### 6.8 Brominated flame retardants

Specific brominated flame retardants such as the  $PBBO_S$  and  $PBB_S$  are not used in this device at all.

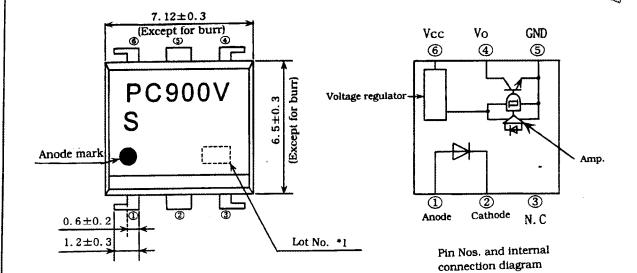
# 7. Notes

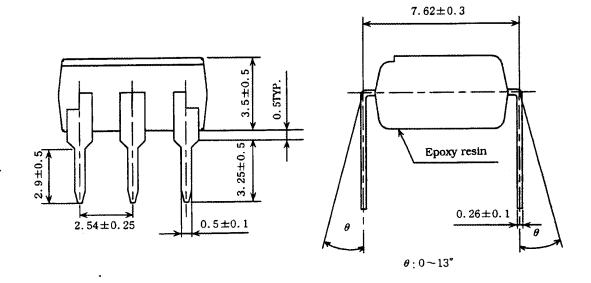
Refer to the attached sheet-1-1, 2.

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#### 2. Outline





- \*1) 2-digit number shall be marked according to DIN standard.
- \*2) Marking is laser marking

Product mass: Approx. 0.36g

_ T T	NIIT	 1 / '	mm
1 1	1 1 1 1		

PC900V

Name Outline Dimensions
(Business dealing

name: PC900V0NSZX)

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# 3. Ratings and characteristics

# 3.1 Absolute maximum ratings

	Parameter	Symbol	Rating	Unit
	*1 Forward current	$I_{\mathbf{F}}$	50	mA
In-must	*2 Peak forward current	I <sub>FM</sub>	1	Α
Input	Reverse voltage	V <sub>R</sub>	6	v
	Power dissipation	P	70	mW
	Supply voltage	Vcc	16 -	v
Output	High level output voltage	V <sub>OH</sub>	16	v
	Low level output current	I <sub>OL</sub>	50	mA
	*1 Power dissipation	Ро	150	mW
*1 Total power dissipation		Ptot	170	mW
*3 Isolation voltage		Viso(rms)	5.0	kV
Operating temperature		Topr	-25 to +85	Ċ
Storage temperature		Tstg	-40 to 125	ಭ
*4 Soldering temperature		Tsol	260	Č

<sup>\*1</sup> The derating factors of absolute maximum ratings due to ambient temperature are shown in Fig. 1, 2, 3.

<sup>\*2</sup> Pulse width≤100 µs, Dutyratio: 0.001

<sup>\*3</sup> AC for 1 min, 40 to 60%RH

<sup>\*4</sup> For 10 s

Rise time

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# 3.2 Electro-optical characteristics

(Onspectified: Ta=O to 70										
		Parameter	Symbol	MIN.	TYP.	MAX.	Unit	Conditions		
Forward valtage		U	-	1.1	1.4	v	I <sub>F</sub> =4mA			
	Forward voltage		$V_{\rm F}$	0.7	1.0	-	V	I <sub>F</sub> =0.3mA		
Input	F	Reverse current	$I_R$	-	-	10	μA	Ta=25°C, V <sub>R</sub> =3V		
	Terminal capacitance		Ct	-	30	250	pF	Ta=25°C, V=0 f=1kHz		
	,	Operating supply voltage ange	Vcc	3	-	15	V	-		
<u>י</u>	L	ow level output voltage	V <sub>OL</sub>	-	0.2	0.4	v	I <sub>OL</sub> =16mA, Vcc=5V I <sub>F</sub> =4mA		
Output	H	ligh level output current	Г <sub>ОН</sub>	-	-	100	μΑ	Vcc=Vo=15V I <sub>F</sub> =0mA		
	L	ow level supply current	I <sub>CCL</sub>	-	2.5	5.0	mA	Vcc=5V, I <sub>F</sub> =4mA		
	High level supply current		I <sub>ссн</sub>	-	1.0	5.0	mA	Vcc=5V, I <sub>F</sub> =0mA		
	"H→L" threshold input current *1		I <sub>FHL</sub>	-	1.1	2.0	mA	Ta=25°C, Vcc=5V R <sub>L</sub> =280Ω		
		current 1		-	-	4.0		Vec=5V, R <sub>L</sub> =280Ω		
tics	"L→H" threshold input		I <sub>FLH</sub>	0.4	0.8	<b>.</b>	mA	Ta=25°C,Vcc=5V R <sub>L</sub> =280 Ω		
cteris		current *2		0.3	-	-		Vcc=5V, $R_L$ =280 $\Omega$		
hara	Hysteresis *3		I <sub>FLH</sub> /I <sub>FHL</sub>	0.5	0.7	0.9	~	Vcc=5V, R <sub>L</sub> =280Ω		
Transfer characteristics	Isolation resistance		Riso	5×10 <sup>10</sup>	1011	-	Ω	Ta=25℃, DC500V 40 to 60%RH		
Tra	"H→L" propagation time		t <sub>PHL</sub>	-	1	3		Ta=25℃		
	nse t	"L→H" propagation time	t <sub>PLH</sub>	-	2	6	μS	Vcc=5V, I <sub>F</sub> =4mA		
	Response	Fall time	tf	-	0.05	0.5	μυ .	$R_1 = 280 \Omega$		
1	Rise time		2	Dice time	tr		0.1	0.5		L

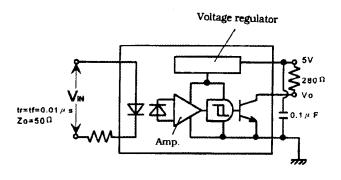
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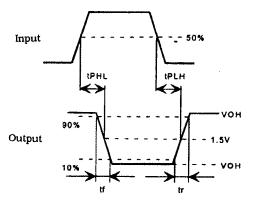
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0.5



- \*1  $I_{\text{FHL}}$  represents forward current when output goes from "H" to "L".
- \*2  $\,\,l_{FLH}$  represents forward current when output goes from "L" to "H".
- \*3 Hysteresis :  $I_{FLH}/I_{FHL}$
- \*4 Test circuit for response time shall be shown below.

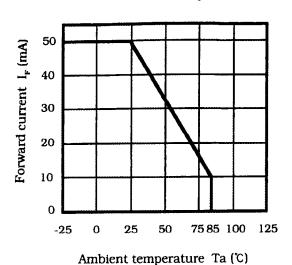




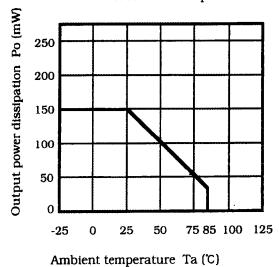
Test circuit diagram

Timing chart

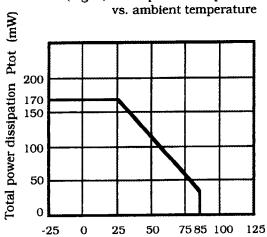
(Fig. 1) Forward current vs. ambient temperature



(Fig. 2) Output power dissipation vs. ambient temperature



(Fig. 3) Total power dissipation



Ambient temperature Ta (℃)

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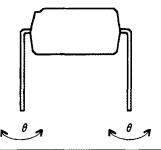
# 4. Reliability

The reliability of products shall be satisfied with items listed below.

Confidence level: 90% LTPD: 10%/20%

Test Items	Test Conditions	Failure Judgement Criteria	Samples (n) Defective(C)
Solderability *2	230°C, 5 s		n=11, C=0
Soldering heat	260℃, 10 s	$V_F>U\times 1.2$	n=11, C=0
Terminal strength (Tension)	Weight: 5N 5 s/each terminal	I <sub>R</sub> >U×2	n=11, C=0
Terminal strength (Bending) *3	Weight: 2.5N 2 times/each terminal	$V_{OL}>U\times1.2$ $I_{OH}>U\times1.2$	n=11, C=0
Mechanical shock	$15$ km/s <sup>2</sup> , 0.5ms $3$ times/ $\pm$ X, $\pm$ Y, $\pm$ Z direction	$I_{CCL}>U\times1.2$ $I_{CCH}>U\times1.2$	n=11, C=0
Variable frequency vibration	100 to 2000 to 100Hz/4min 200m/s <sup>2</sup> 4 times/ X, Y, Z direction	I <sub>FHL</sub> >U×1.3	n=11, C=0
Temperature cycling	1 cycle -40℃ to +125℃ (30min) (30min) 20 cycles test	$I_{\text{FLH}} < L \times 0.7$ $I_{\text{FLH}} / I_{\text{FHL}} \neq L \times 0.8$ $\sim U \times 1.2$	n=22,C=0
High temp. and high humidity storage	+85°C. 85%RH. 1000h	U : Upper specification	n=22,C=0
High temp. storage	+125°C, 1000h	limit	n=22,C=0
Low temp. storage	-40°C, 1000h	L: Lower	n=22,C=0
Operation life	I <sub>F</sub> =10mA, Vcc=15V I <sub>OL</sub> =16mA, Ta=25°C, 1000h	specification limit	n=22,C=0

- \*1 Test method, conforms to EIAJ ED 4701.
- \*2 Solder shall adhere at the area of 95% or more of immersed portion of lead, and pin hole or other holes shall not be concentrated on one portion.
- \*3 Terminal bending direction is shown below.



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- 5. Outgoing inspection
  - 5.1 Inspection items
  - (1) Electrical characteristics

 $\rm V_{\rm F}, \, \rm I_{\rm R}, \, \rm V_{\rm OL}, \, \rm I_{\rm OH}, \, \rm I_{\rm CCL}, \, \rm I_{\rm CCH}, \, \rm I_{\rm FHL}, \, \rm I_{\rm FLH}, \, Riso, \, Viso$ 

- (2) Appearance
- 5.2 Sampling method and Inspection level

A single sampling plan, normal inspection level II based on ISO 2859 is applied. The AQL according to the inspection items are shown below.

Defect	Inspection item	AQL (%)
Major defect	Electrical characteristics Unreadable marking	0.065
Minor defect	Appearance defect except the above mentioned.	0.25

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sheet-1-1

# Precautions for Photocouplers

### 1 For cleaning

(1) Solvent cleaning: Solvent temperature 45°C or less Immersion for 3 min or less

(2) Ultrasonic cleaning: The effect to device by ultrasonic cleaning differs

by cleaning bath size, ultrasonic power

output, cleaning time, PCB size or device mounting condition etc. Please test it in actual using condition and confirm that doesn't occur any defect before starting

the ultrasonic cleaning.

(3) Applicable solvent: Ethyl alcohol, Methyl alcohol, Isopropyl alcohol

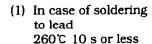
In case when the other solvent is used, there are cases that the packaging resin is eroded. Please use the other solvent after thorough confirmation is performed in actual using condition.

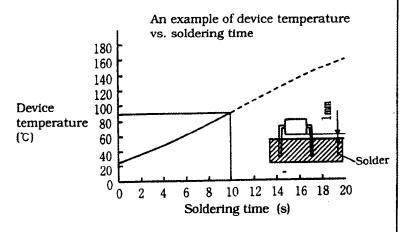
- 2. Please use the same as normal integration circuit about static electricity in order that this device is OPIC photocoupler.
- 3. In order to stabilize power supply line, we recommend to connect a by-pass capacitor of  $0.01\,\mu\text{F}$  or more between Vcc and GND near the device.
- 4. The detector which is used in this device, has parasitic diode between each pins and GND. There are cases that miss operation or destruction possibly may be occurred if electric potential of any pin becomes below GND level even for instant.

  Therefore it shall be recommended to design the circuit that electric potential of any pin does not become below GND level.
- 5. The LED used in the Photocoupler generally decreases the light emission power by operation. In case of long operation time, please design the circuit with considering the decreases of the light emission power of the LED. (50%/5years) Please decide the input current which become 2 times of MAX. I<sub>FHL</sub>.

PAGE
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sheet-1-2

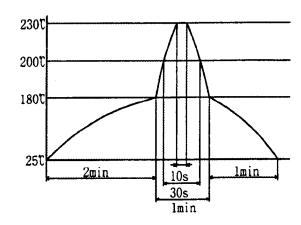
### 6. Precautions for Soldering Photocouplers





### (2) If solder reflow:

It is recommended that only one soldering be done at the temperature and the time within the temperature profile as shown in the figure below.



# (3) Other precautions

An infrared lamp used to heat up for soldering may cause a localized temperature rise in the resin. So keep the package temperature within that specified in Item (2). Also avoid immersing the resin part in the solder.



### Package specification

### 1 Package materials

No.	Name	Materials	Purposes
1	Sleeve	Plastics with preventing static electricity	Products packaged
2	Stopper	Rubber	Products fixed
3	Packing case	Corrugated cardboard	Sleeve packaged
4	Kraft tape	Paper	Lid of packaged case fixed
5	Label	Paper	Model No., quantity, inspection date and lot No. specified

### 2 Package method

- (1) MAX. 50pcs. of products shall be packaged in a sleeve and both of sleeve edges shall be fixed by stoppers.
- (2) MAX. 20 sleeves above shall be packaged in a packing case and pack a sheet of cushion at one side.
- (3) Model No., quantity, inspection date and lot No. shall be marked on the label and this label shall be put on the side of the packaging case.
- (4) Case shall be closed with the lid and enclosed with kraft tape.

### 3 Package outline dimensions

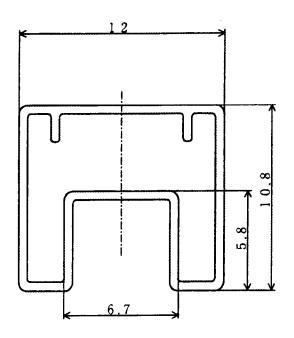
(1) Sleeve outline dimensions

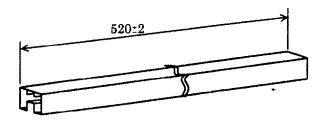
Refer to the attached sheets-2-2.

(2) Packaging case outline dimensions

Refer to the attached sheets-2-3.

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sheets-2-2





Length : L=520  $\pm$  2mm

Note 1) Thickness: 0.5±0.2mm

2) Outer R: 0.5mm

3) Process with applying antistatic agent.

4) Unless otherwise specified tolerances shall be  $\pm 0.5$ mm. (However except for deformation due to the rubber stopper in sleeve.)

Unit: 1/1mm

Name

Sleeve outline dimensions

